

SAW Components

SAW Filter

Cellular / LTE / Band 39

Series type: QGSA1G90AASP2

Ordering code: QGSA1G90AASP2

Date: October 2021

Version: 1.0



These materials, including the information contained herein, may be used only for informational purposes by the customer. QuantGrav assume no responsibility for errors or omissions in these materials or the information contained herein. QuantGrav reserve the right to make changes to the product(s) or information contained herein without notice. The materials and information are provided on an AS IS basis, and QuantGrav assume no liability and make no warranty or representation, either expressed or implied, with respect to the materials, or any output or results based on the use, application, or evaluation of such materials, including, without limitation, with respect to the non-infringement of trademarks, patents, copyrights or any other intellectual property rights or other rights of third parties.

No use of this documentation or any information contained herein grants any license, whether express, implied, by estoppel or otherwise, to any intellectual property rights, including, without limitation, to any patents owned by Hubei QuantGrav Technology Co., Ltd.

Not to be used, copied, reproduced, or modified in whole or in part, nor its contents revealed in any manner to others without the express written permission of Hubei QuantGrav Technology Co., Ltd.

QuantGrav is trademarks of Hubei QuantGrav Technology Co., Ltd., registered in the people's Republic of China.

Contents

1 Applications	3
2 Features	3
3 Package	4
4 Pin configuration	4
5 Matching circuit	5
6 Absolute Maximum Ratings	5
7 Characteristics	6
8 Transmission coefficients	7
9 Soldering profile	8
10 Tape and Reel	9
10.1 Tape	9
10.2 Reel with diameter of 178 mm	9

1 Applications

- Low-loss SAW RF filter for Cellular/Cordless phone (Terminal)relevant market only.
- SAW for B39Rx
- 1880-1920MHz

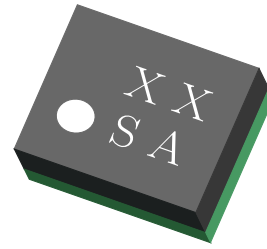
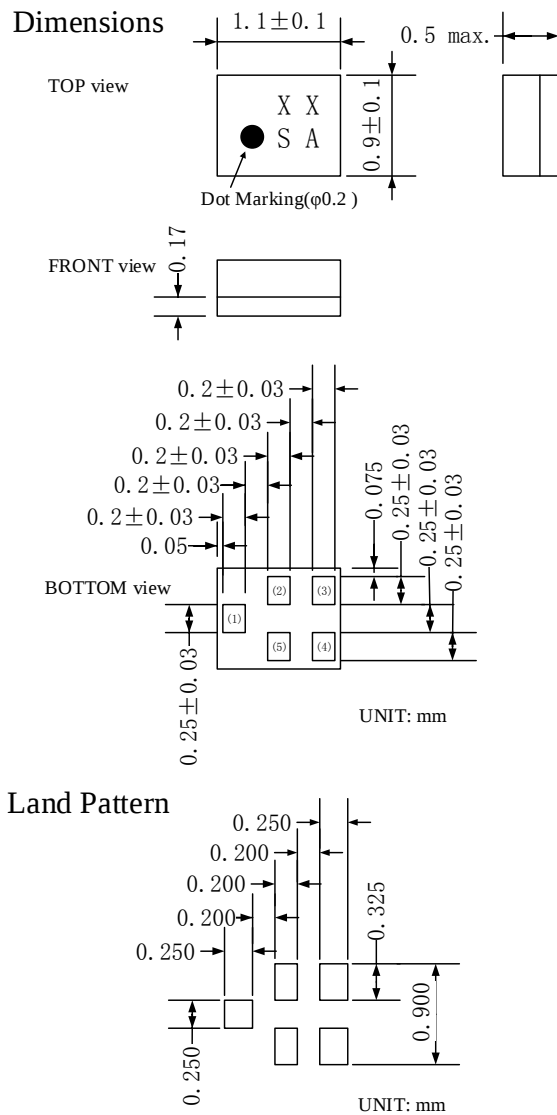


Figure 1: Picture of component with example of product marking.

2 Features

- Package size 1.1 mm x 0.9 mm
- Package height 0.5 mm (max.)
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 3 (MSL3)

3 Package



4 Pin configuration

- 1 Input
- 4 Output
- 2,3,5 Ground

Figure 2: Drawing of package with package height A = 0.5 mm (max.)

5 Matching circuit

- $R_1 : 50\Omega$ $R_2 : 50\Omega$

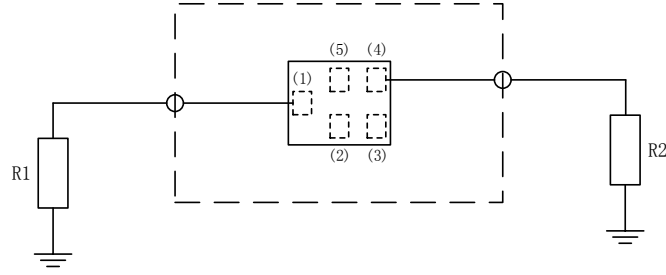


Figure 3: Schematic of matching circuit.

6 Absolute Maximum Ratings

Table 1: Absolute Maximum Ratings of Example Data Sheet

Parameter	Rating
Storage temperature	$T_{STG} = -40^{\circ}C$ to $+95^{\circ}C$
Operating temperature	$T_{opt} = -20^{\circ}C$ to $+85^{\circ}C$
DC voltage	$V_{DC} = 3.0V(max)$
Input power ¹	$P_{IN} = +13dBm$ 5000h $+55^{\circ}C$

¹Input signal shall be applied to TX port.

7 Characteristics

Temperature range for specification $T_{SPEC} = -20^{\circ}C \dots +85^{\circ}C$

Input terminating impedance $Z_{IN} = 50\Omega$

Output terminating impedance $Z_{OUT} = 50\Omega$

Item		min.	typ.	max.	Unit	Note
Center Frequency		1900			MHz	
Insertion Loss	1880 to 1920 MHz		1.4	2.0		
Ripple Deviation	1880 to 1920 MHz		0.5	1.4	dB	
VSWR	1880 to 1920 MHz		1.4	2.0		
Absolute Attenuation	450 to 1710 MHz	30	35		dB	
	1710 to 1805 MHz	35	43		dB	
	1805 to 1840 MHz	35	41		dB	
	1840 to 1850 MHz	30	43		dB	
	2000 to 2110 MHz	30	41		dB	
	2110 to 2200 MHz	33	36		dB	
	2200 to 4000 MHz	30	38		dB	
	4000 to 6000 MHz	27	34		dB	

8 Transmission coefficients

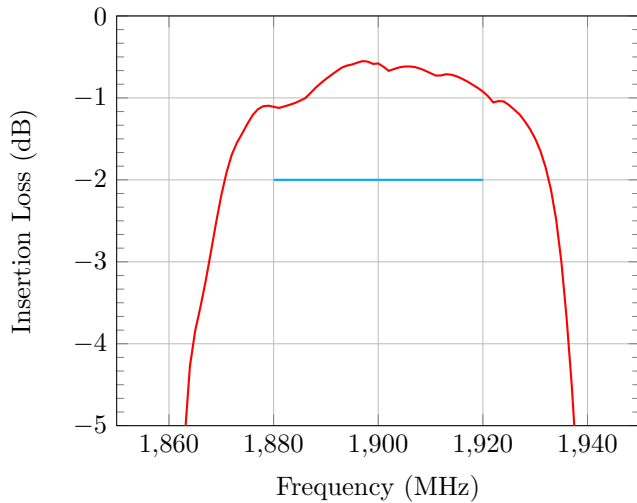


Figure 4: Passband

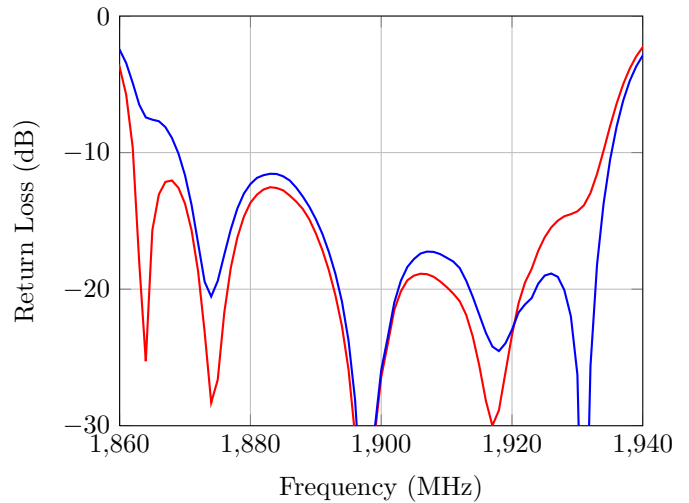


Figure 5: Input/Output Return Loss

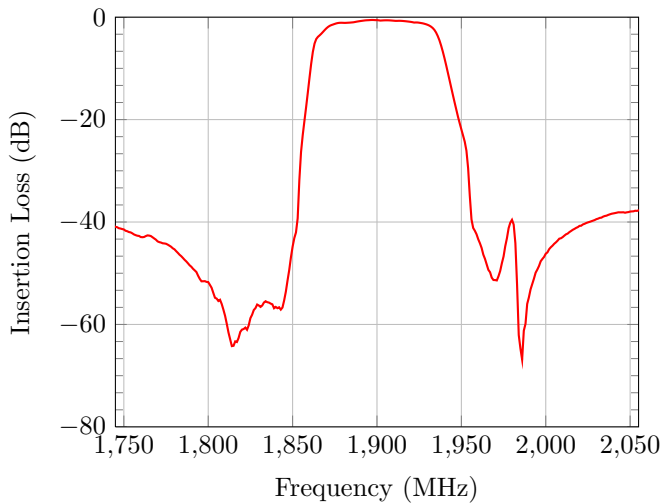


Figure 6: Narrowband

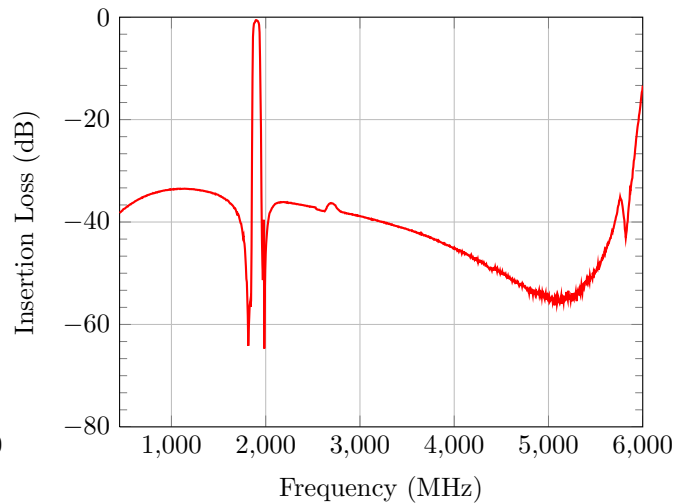
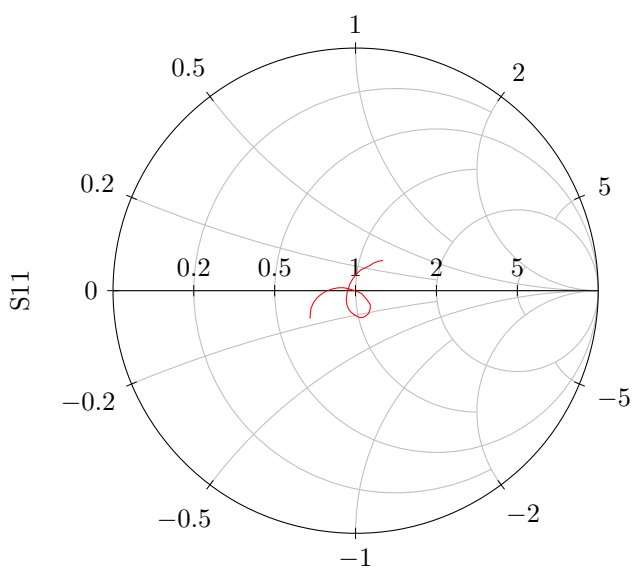
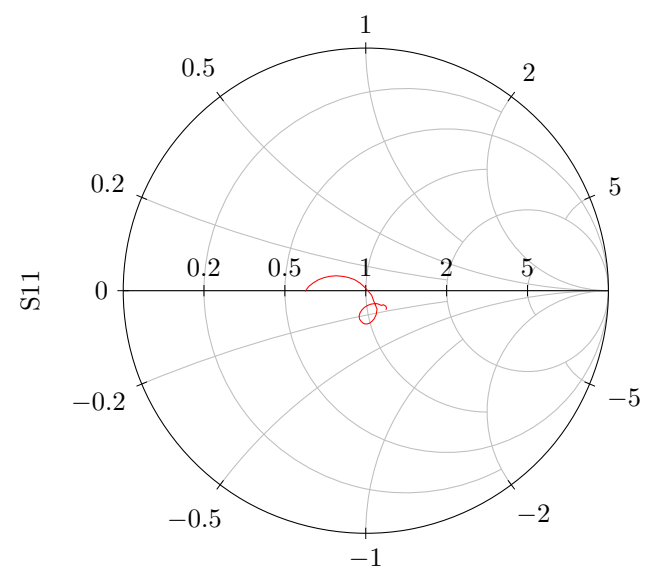


Figure 7: Wideband

Figure 8: Input Smith Chart ($Z_0 = 50\Omega$)Figure 9: Output Smith Chart ($Z_0 = 50\Omega$)

9 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58-3rd edit and IPC/JEDECJ-STD-020B.

Table 2: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

Parameter	Rating
Ramp rate	≥ 3 K/s
Preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T >220 °C	30 s to 70 s
T >230 °C	Min. 10 s
T >245 °C	Max. 20 s
T $\leq$ 255 °C	-
Peak temperature T_{peak}	220 °C $\pm$ 5°C
Wetting temperature T_{min}	230 °C $\pm$ 5°C for 10s $\pm$ 1s
Cooling rate	≥ 3 K/s
Soldering temperature T	Measured at solder pads

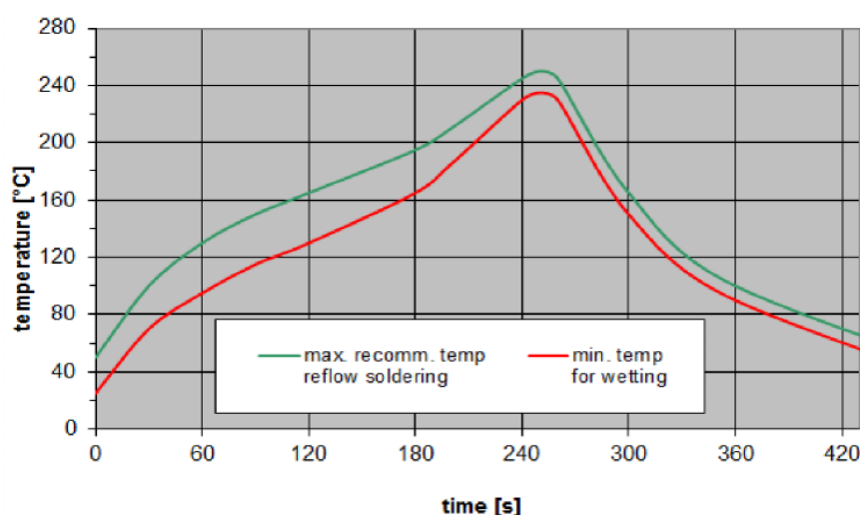


Figure 10: Drawing of reel (Recommended reflow profile for convection and infrared soldering – lead-free solder)

10 Tape and Reel

10.1 Tape

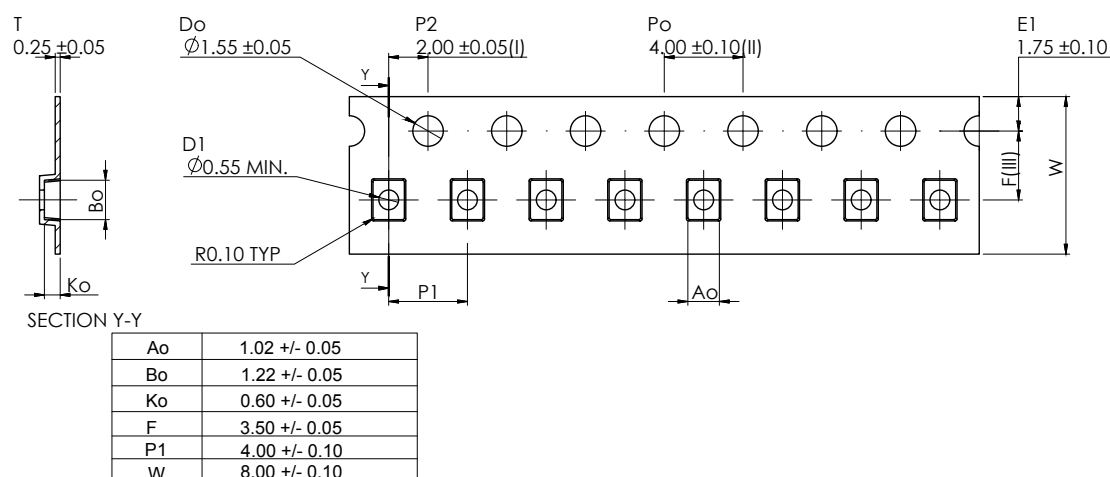


Figure 11: Drawing of tape (first-angle projection) with tape dimensions

10.2 Reel with diameter of 178 mm

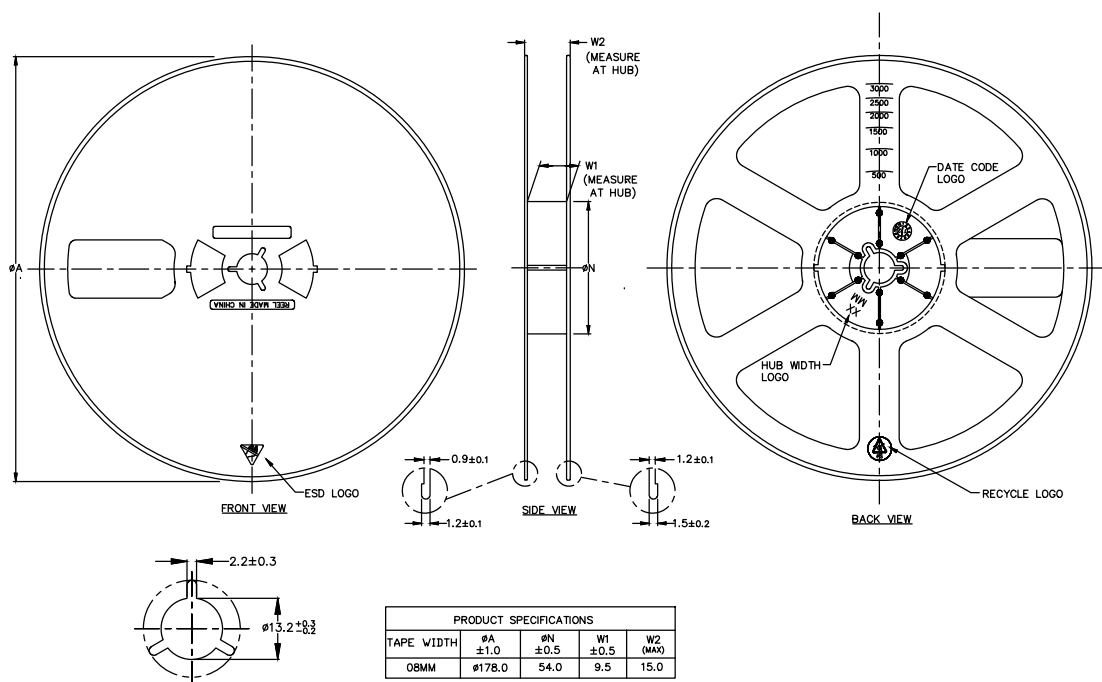


Figure 12: Drawing of reel (first-angle projection) with diameter of 180 mm